

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

Claims 1-8 (canceled)

1                    9. (original) A method of making a chip device, the method comprising:  
2                    providing a die;  
3                    providing a leadframe including a die attach cavity and a plurality of dimples  
4 defined around a periphery of the leadframe, the die attach cavity having substantially the  
5 same thickness as the die;  
6                    placing solder balls into the dimples; and  
7                    flipping the die into the die attach cavity and attaching it therein.

1                    10. (original) The method of claim 9 wherein the die provided is a bumped  
2 die.